

## N-CHANNEL 30V - 0.0045 Ω - 17A SO-8 STripFET™ II MOSFET FOR DC-DC CONVERSION

ТҮРЕ	V <sub>DSS</sub>	R <sub>DS(on)</sub>	ID
STS17NF3LL	30 V	<0.0055 Ω	17 A

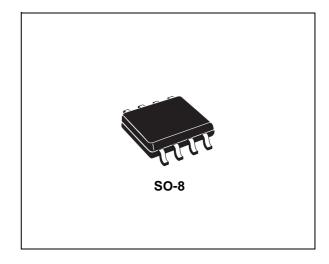
- TYPICAL R<sub>DS</sub>(on) = 0.0045 Ω @ 10V
- OPTIMAL R<sub>DS</sub>(on) x Qg TRADE-OFF @ 4.5V
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

#### DESCRIPTION

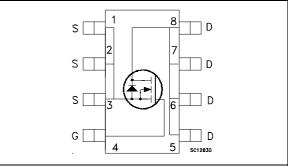
This application specific Power MOSFET is the second generation of STMicroelectronis unique "Single Feature Size<sup>™</sup>" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. Such features make it the best choice in high efficiency DC-DC converters for Telecom and computer industries.

#### APPLICATIONS

- DC-DC CONVERTERS FOR TELECOM AND NOTEBOOK CPU CORE
- SYNCHRONOUS RECTIFIER



#### INTERNAL SCHEMATIC DIAGRAM



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
V <sub>DGR</sub>	Drain-gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	30	V
V <sub>GS</sub>	Gate- source Voltage	± 18	V
I <sub>D</sub>	Drain Current (continuous) at $T_C = 25^{\circ}C$	17	A
ID	Drain Current (continuous) at T <sub>C</sub> = 100°C	12	A
I <sub>DM</sub> (●)	Drain Current (pulsed)	68	A
P <sub>tot</sub>	Total Dissipation at $T_C = 25^{\circ}C$	3.2	W

(•) Pulse width limited by safe operating area.

March 2003

#### THERMAL DATA

Rthj-amb(*)Thermal Resistance Junction-ambientRthj-leadThermal Resistance Junction-leadsTjMaximum Operating Junction TemperatureTstqStorage Temperature	Max Max	47 16 -55 to 175 -55 to 175	°C/W °C/W °C °C
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(\*) When Mounted on 1 inch<sup>2</sup> FR-4 board, 2 oz of Cu and t  $\leq$  10 sec.

## **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25 \text{ °C}$ unless otherwise specified)

#### OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	30			V
IDSS	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS}$ = Max Rating $V_{DS}$ = Max Rating T <sub>C</sub> = 125°C			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 18 V			±100	nA

#### ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250 μA	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 8.5 A I <sub>D</sub> = 8.5 A		0.0045 0.0055	0.0055 0.007	$\Omega \ \Omega$

#### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	$V_{DS} = 10 \text{ V}$ $I_D = 8.5 \text{ A}$		37		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		2160 614 98		pF pF pF

#### ELECTRICAL CHARACTERISTICS (continued)

#### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time			23.5 39		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD}=24V$ I <sub>D</sub> =12.5A V <sub>GS</sub> =4.5 V (see test circuit, Figure 2)		26 7 12	35	nC nC nC

#### SWITCHING OFF

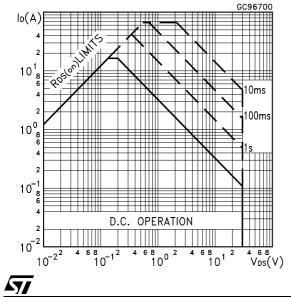
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time	$V_{DD} = 15 V$ R <sub>G</sub> = 4.7 $\Omega$ , (Resistive Load	I <sub>D</sub> = 8.5 A V <sub>GS</sub> = 4.5 V , Figure 3)		47.5 37		ns ns

#### SOURCE DRAIN DIODE

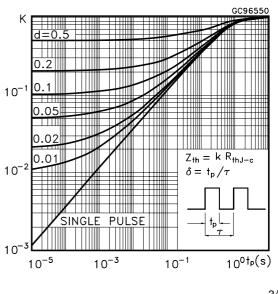
Symbol	Parameter	eter Test Conditions		Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (●)	Source-drain Current Source-drain Current (pulsed)					17 68	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 17 A	$V_{GS} = 0$			1.2	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 17 \text{ A}$ $V_{DD} = 15 \text{ V}$ (see test circui	di/dt = 100A/µs T <sub>j</sub> = 150°C t, Figure 3)		39 45 2.3		ns nC A

(\*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

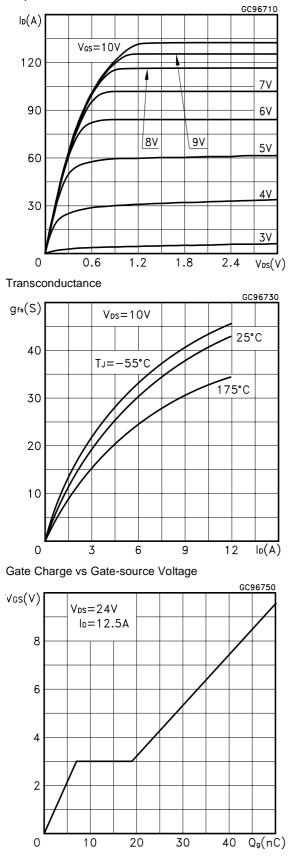
Safe Operating Area

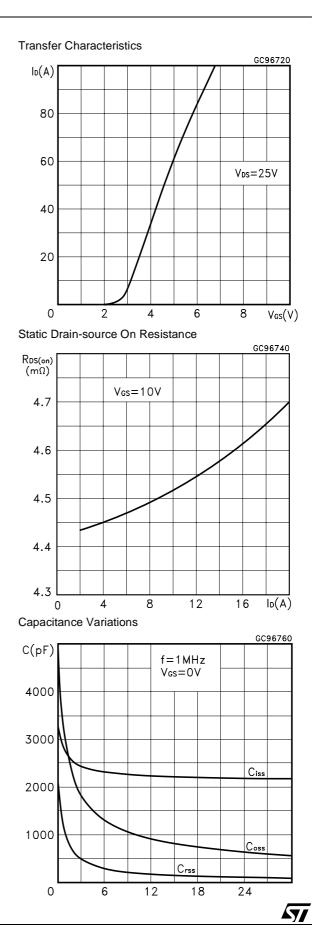


Thermal Impedance

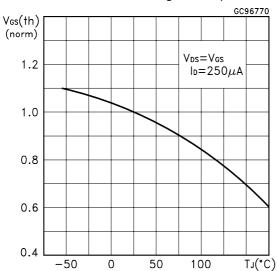


#### **Output Characteristics**



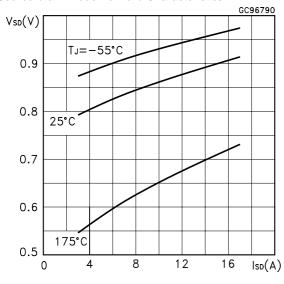


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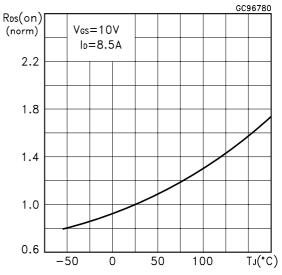


Normalized Gate Threshold Voltage vs Temperature

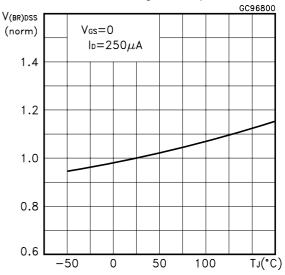
Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage vs Temperature.



**Fig. 1:** Switching Times Test Circuits For Resistive Load

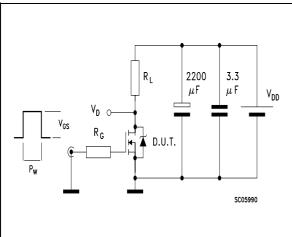
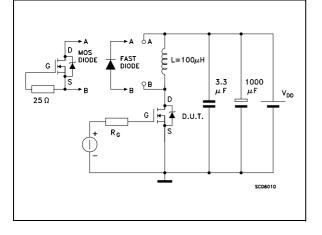
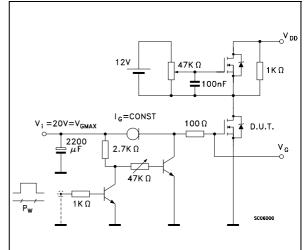


Fig. 3: Test Circuit For Diode Recovery Behaviour



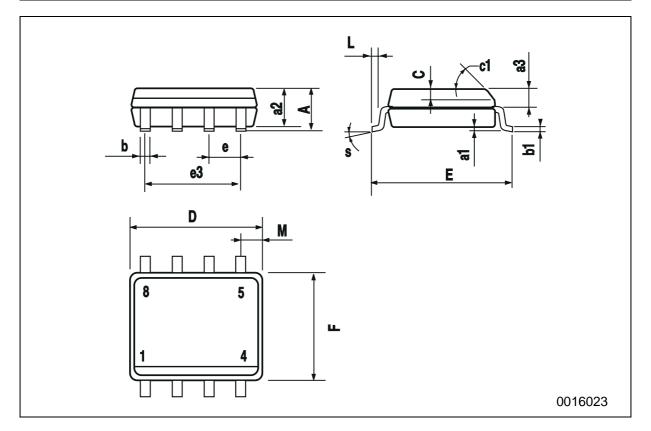
#### Fig. 2: Gate Charge test Circuit



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DIM.		mm			inch	
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)		





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